

5116S/L 2K x 8-BIT CMOS STATIC RAM

	5116S-10	5116S-12	Unit
Address Access Time (t _{AA})	100	120	ns
Chip Select Access Time (t _{ACS})	100	120	ns
Output Enable Access Time (t _{OE})	40	50	ns

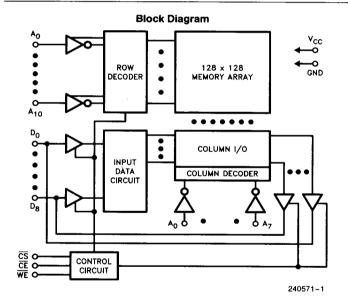
- Static Operation
 - No Clock/Refresh Required
- Equal Access and Cycle Times

 Simplifies System Design
- Single +5V Supply

- Power Down Mode
- TTL Compatible
- Common Data Input and Output
- High Reliability 24-Pin 600 Mil PDIP Package

The 5116S is a 2048-word by 8-bit CMOS static RAM fabricated using CMOS Silicon Gate process.

When the Chip Select is brought high, the device assumes a standby mode in which the standby current is reduced to 2 μ A (max). The 5116S has a data retention mode that guarantees that data will remain at minimum power supply voltage of 2.0V.



Pin Connections 24 b v_{cc} ᄻᆸ 23 A8 ᇯᅥ 22 Ag 21 1 WE 20 🗖 ŌĒ ᄱᄱ 19 🗖 🗛 18 🗖 CS $A_1 \square$ ᄱᅄ 17 07 ь**, Ц** 9 16 D₆ D₁ 10 15 D₅ D₂ 🗖 11 14 D D4 GND 12 13 D D 2 240571-2

Pin Names

Address Input
Data Input/Output
Chip Select Input
Write Enable Input
Output Enable Input
Power
Ground

October 1989 Order Number: 240571-002



Device Operation

The 5116S has two control inputs: Chip Select (\overline{CS}) and Write Enable (\overline{WE}). \overline{CS} is the power control pin and should be used for device operation. \overline{WE} is the data control pin and should be used to gate data at the I/O pins.

Standby Power

The 5116S is placed in a standby or reduced power consumption mode by applying a high (V_{IH}) to the $\overline{\text{CS}}$ input. When in standby mode, the device is deselected and the outputs are in a high impedance state, independent of the $\overline{\text{WE}}$ input.

Table 1. Mode Selection Truth Table

CS	WE	ŌĒ	Mode	1/0	Power
Н	Х	Х	Standby	High Z	Standby
L	L	Х	Write	D _{IN}	Active
L	Н	L	Read	D _{OUT}	Active
L	Х	Н	Read	High Z	Active

Write Mode

Write Cycles may be controlled by either \overline{WE} or \overline{CS} . In either case, both \overline{WE} and \overline{CS} must be high (V_{IH}) during address transitions. During a \overline{WE} Controlled write cycle, \overline{CS} must be held low (V_{IL}) while \overline{WE} is low. Address transfers occur on the falling edge of \overline{WE} and the data transfers on rising edge of \overline{WE} . During a \overline{CS} controlled cycle, \overline{WE} must be held low (V_{IL}) while \overline{CS} is low. The addresses are then transferred on the falling edge of \overline{CS} and data on the rising edge of \overline{CS} . Data, in both cases, must be valid for a time t_{DW} before the controlling input is brought high (V_{IH}) and remain valid for a time t_{DH} after the controlling input is high.

Read Mode

 $\overline{\text{CS}}$ must be low (V_{IL}) and $\overline{\text{WE}}$ must be high (V_{IH}) to activate a read cycle and obtain data at the outputs. Given stable addresses, valid data is available after a time t_{AA} .

ABSOLUTE MAXIMUM RATINGS*

Voltage on Any Pin Relative
to Ground (V_{IN} , V_{OUT}) – 0.3V to + 7V
Storage Temperature (T _{stg})55°C to +150°C
Power Dissipation (PD)1.0W
DC Continuous Output Current (IOS)50 mA

NOTICE: This is a production data sheet. The specifications are subject to change without notice.

*WARNING: Stressing the device beyond the "Absolute Maximum Ratings" may cause permanent damage. These are stress ratings only. Operation beyond the "Operating Conditions" is not recommended and extended exposure beyond the "Operating Conditions" may affect device reliability.

RECOMMENDED OPERATING CONDITIONS Voltage referenced to V_{SS}, T_A = 0°C to 70°C

Symbol	Parameter	Min	Тур	Max	Unit
V _{CC}	Supply Voltage	4.5	5.0	5.5	V
V _{SS}	Ground	0	0	0	V
V _{IH}	Input High Voltage	2.2		V _{CC} +0.3	٧
V _{IL}	Input Low Voltage	-0.3		0.8	V

NOTE:

CAPACITANCE T_A = 25°C, f = 1.0 MHz

Symbol	Parameter	Min	Max	Unit
C _{IN1}	Input Capacitance (V _{IN} = 0V)		6	pF
C _{OUT}	Output Capacitance (V _{OUT} = 0V)		8	pF

NOTE:

This parameter is sampled and not 100% tested.

^{1.} During transitions, the inputs may undershoot to -3.5V for periods less than 20 ns.



D.C. AND OPERATING CHARACTERISTICS

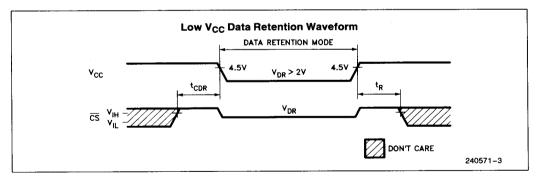
Recommended Operating Conditions unless otherwise noted

Symbol	Parameter		Min	Тур	Max	Units	Test Conditions
I _{CC1}	Operating Current Dynamic Current			30	40	mA	V _{CC} = Max, $\overline{\text{CS}}$ = V _{IL} Outputs open
lcc2				30	60	mA	T _{cyc} = Min, V _{CC} = Max Outputs open
I _{SB}					3	mA	CS = V _{IH}
I _{SB1}	Standby Current	STD		4	50	μΑ	$\overline{\text{CS}} \ge V_{\text{CC}} - 0.2V$
		L		0.2*	2] "	$V_{IN} = GND \text{ to } V_{CC}$
ILI	Input Load Current		-1		1	μΑ	$V_{CC} = Max$ $V_{IN} = GND \text{ to } V_{CC}$
l _{LO}	Output Leakage		1		1	μА	$\overline{\text{CS}} = \text{V}_{\text{IH}}, \text{V}_{\text{CC}} = \text{Max}$ $\text{V}_{\text{OUT}} = \text{GND to V}_{\text{CC}}$
V _{OH}	Output High Voltage		2.4			V	$I_{OH} = -1.0 \text{ mA}$
V _{OL}	Output Low	/ Voltage			0.4	٧	I _{OL} = 2.1 mA

^{*}T_A = 25°C

DATA RETENTION ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
V _{CDR}	Voltage for Data Retention		2			V
ICCDR	Data Retention Current	$eq:continuous_continuous$		0.05	2	μА
t _{CDR}	Chip Deselect to Data Retention Time		0			ns
t _R	Operation Recovery Time		t _{RC}			ns



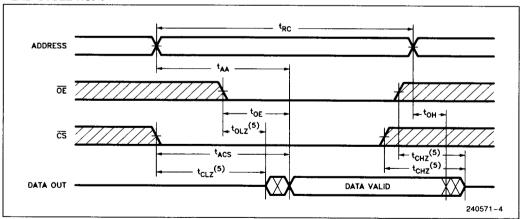
A.C. TEST CONDITIONS	Timing Reference Level
Input Pulse Levels 0.8V to 2.4V	Output Load 1 TTL Load + 100 pF
Input Rise and Fall Times	

A.C. CHARACTERISTICS $T_A = 0^{\circ}C$ to $70^{\circ}C,\,V_{CC} = 5V\,\pm10\%$

READ CYCLE

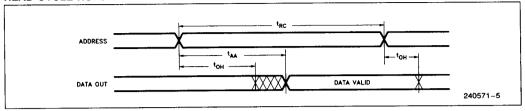
Symbol	Parameter	5110	6S-10	5116	SS-12	Unit
	1 2.4	Min	Max	Min	Max	Onit
t _{RC}	READ Cycle Time	100		120		ns
t _{AA}	Address Access Time		100		120	ns
tACS	Chip Select Access Time		100		120	ns
tон	Output Hold from Address Change	10		10		ns
^t CLZ	Chip Selection to Output in Low Z	10		10	-	ns
t _{CHZ}	Chip Deselection to Output in High Z	0	40	0	40	ns
t _{OE}	Output Enable Access Time	40		50		ns
t _{OLZ}	Output Enable to Output in Low Z	10		10		ns
tонz	Output Enable to Output in High Z	0	40	0	40	ns

READ CYCLE NO. 1(1)

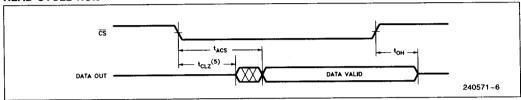




READ CYCLE NO. 2(1, 2, 4)



READ CYCLE NO.3(1, 3, 4)



- 1. WE is high for READ Cycle. The first transitioning address.

 2. Device is continuously selected; $\overline{CS} = V_{\parallel L}$.

 3. Address valid prior to or coincident with \overline{CS} transition low.

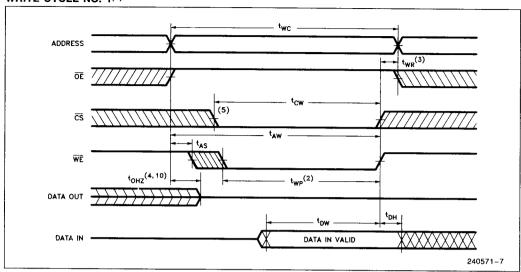
- 4. $\overline{OE} = V_{IL}$.
- 5. Transition is measured at \pm 500 mV from steady state voltage.

A.C. CHARACTERISTICS $T_A = 0$ °C to 70°C, $V_{CC} = 5V \pm 10$ % (Continued)

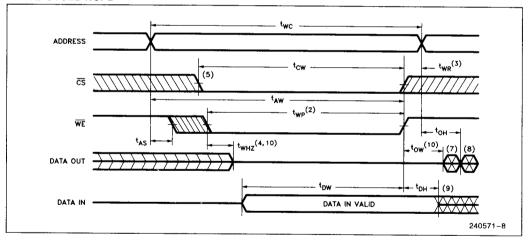
WRITE CYCLE

Symbol	Parameter	5116	S-10	5116S-12		Unit
	raidilletei	Min	Max	Min	Max	
twc	WRITE Cycle Time	100		120		ns
t _{CW}	Chip Selection to End of Write	65		70		ns
t _{AW}	Address Valid to End of Write	80		105		ns
tas	Address Set-Up Time	0		0		ns
t _{WP}	Write Pulse Width	60		70		ns
twR	Write Recovery Time	10		10		ns
t _{DW}	Data Valid to End of Write	30		35		ns
t _{DH}	Data Hold Time	10		10		ns
twHZ	Write Enable to Output in High Z	0	30	0	35	ns
tow	Output Active from End of Write	10		10		ns
tонz	Output Disable to Output in High Z	0	40	0	40	ns

WRITE CYCLE NO. 1(1)



WRITE CYCLE NO. 2(1, 6)



NOTES:

- 1. WE must be high during address transitions.
- 2. A Write occurs during the overlap (twp) of a low CS and a low WE.
- 3. All Write Cycle timings are referenced from the last valid address to the first transitioning address.
- 4. During this period, I/O pins are in tri-state.
- 5. If the CS low transition occurs simultaneously with the WE low transitions or after the WE transition, outputs remain in tristate.
- 6. \overline{OE} is continuously low ($\overline{OE} = V_{IL}$).
- 7. DOUT is the same phase of write data on this write cycle.
- 8. Dour is the read data of next address.
 9. If CS is low during this period, I/O pins are in output state.
- 10. Transition is measured at ±500 mV from steady state voltage.

PACKAGE OUTLINE

